SCF5249LAG120 :Part Detail

Product Summary Page | General Information | Package Information | Environmental and Compliance Information | Manufacturing Information | Ordering Information | Product/Process Change Notice (PCN) | Operating Characteristics | Reliability Data Lookup

General Information

Part Number	SCF5249LAG120
Description	AUDIO COLDFIRE LOW PWR
Product Line	GGG5249N
PTI	MBUC
Material Type	Tested Packaged Device
Life Cycle Description (code)	NOT RECOMMENDED(DECLINING)
Status	Not Recommended for New Design
Application/Qualification Tier	10-YEARS APPLICATION LIFE

Package Information

Package Type and Termination Count	LQFP 144
Package Description and Mechanical Drawing	LQFP 144 20*20*1.4P0.5
Device Weight(g)	1.31910
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	20.000
Package Width (nominal)(mm)	20.000
Package Thickness (nominal)(mm)	1.500
Maximum Height Above Board(mm)	1.600
Tape & Reel	No

Environmental and Compliance Information

Pb-Free	
RoHS Compliant	
Halogen Free	Yes
Material Composition Declaration (MCD)	Download MCD Report Download MCD Report
RoHS Certificate of Analysis (CoA)	Download RoHS CoA Report

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2nd Level Interconnect	**e3**
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement
UL94 (plastics flammability test)	V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

Manufacturing Information

Micron Size(µm)	.18

Ordering Information

Minimum Package Quantity (MPQ)	300
MPQ Container	BRICK
Exempt from Minimum Delivery Value	No
Preferred Order Quantity (POQ)	300
POQ Container	BOX
Export Control Classification Number (US)	3A991A2
Harmonized Tariff (	
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US Currency	-
Device Sample Availability	20 Feb 2004
Device Production Availability	20 Feb 2004
Order	

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
12469	Product Change Notice	TSPG MCD32 20X20 LQFP MATERIAL CHANGE	21 Dec 2006	21 Mar 2007
11462	Product Bulletin	TSPG MCD ROHS COMPLIANT DEVICE MIGRATION	14 Oct 2005	15 Oct 2005
11431	Product Bulletin	TSPG MCD ROHS COMPLIANT DEVICE MIGRATION	04 Oct 2005	05 Oct 2005
10742	Product Bulletin	KLM PACKING CHANGE FOR TRAY DEVICES	28 Mar 2005	02 Apr 2005

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10323	Product Change Notice	TRAY MATERIAL CHANGE FOR LQFP 2020 1.4.	29 Sep 2004	02 Jan 2005
10031	Product Bulletin	RE-ISSUE TSPG-TECD PB-FREE PACKAGE QUALIFICATION	18 Jun 2004	19 Jun 2004
9845	Product Bulletin	TSPG-TECD PB-FREE PACKAGE QUALIFICATION	06 May 2004	07 May 2004

Operating Characteristics

ADC (bit)	12
ADC (ch)	4
Additional Features	Flash Media Interface PLL
Ambient Operating Temperature (Min-Max) (°C)	0 to 70
Bus Frequency (Max) (MHz)	120
Cache (KB)	8
Chip Selects	4
External Memory Supported	SDRAM
GPIOs	47
I/O Operating Voltage (Max) (V)	3.6
I2C	1
Internal RAM (KB)	96
Operating Frequency (Max) (MHz)	140
QSPI	1
Sample Exception Availability	N
Timer Features	Reference Compare Output Compare Input Capture
Timers	2-ch. 16 bit
Total DMA Channels	4
UART	2

Reliability Data Lookup

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